

Banpil Announces Satori Group as Japan Distributor for Low-Power High-Speed Interconnect Products

SANTA CLARA, California -- January 3, 2012 -- Banpil Photonics, Inc., a leading company expanding tomorrow's technology through innovations in optics and electronics, today announced that it has signed an agreement with the Satori Group's flagship company, Satori Electric Co., LTD, to become a Japan Distributor for Banpil's high-speed metallic (electrical) interconnects technology products and services.

Satori Electric, www.satori.co.jp, headquartered in Tokyo, Japan is a global company listed on the Tokyo Stock Exchange and specializes in the distribution of integrated circuits (ICs), discrete semiconductors, general electronic components and electronic equipment. Satori Group is also involved in the development and production of information control systems and switching devices, as well as design of microprocessors and application specific ICs (ASICs) on behalf of customers.

"We are very pleased to bring Satori Electric on board as our first international distributor serving Japan," said Dr. Achyut Dutta, Banpil's CEO. "We are confident that Banpil's Interconnect products and services will be welcomed and much demanded by leading system vendors and PCB manufacturers in efforts to develop next generation 40G to 100G high-speed systems with low-power consumption. We look forward to working with Satori Group to reach Japanese customers."

Among the products available through Satori Electric include (1) Banpil's low-power and high-speed metallic Interconnects Technology comprising of Licensing Intellectual Property of nearly 30 Patents; (2) Banpil's Interconnects Design Software including S-Factor Simulation Tools and the Agilent ADS Compatible Simulation Library; and (3) Banpil Services for Advanced High-Speed Systems, which include testing, training, and consulting services provided by Banpil.

Banpil has already demonstrated the implementation and superior performance of its patented technology. The company demonstrated 20 Gb/s per channel on a 3-meter long flexible-printed-circuit (FPC) and 40 Gb/s per channel over 1-meter FPC. Earlier, Banpil demonstrated 10 Gb/s signals over a 1.5-meter long rigid FR4 printed circuit board (PCB) and 20 Gb/s on a 1-meter long FR4-PCB. The remarkable channel efficiency of Banpil's metallic interconnects in both conventional LF-FPCs and FR4-PCB make it possible to increase signal-carrying capacity by more than 6 times over conventional solutions, while reducing power consumption by as much as 90%.

Banpil is working with global system vendors and PCB manufacturers to deploy its low-power high-speed interconnect technologies into next-generation products such as high-speed routers, switches, servers, and other communications and computing systems. Banpil welcomes opportunities to explore new or enhanced applications with system vendors as well as manufacturing partnerships with PCB manufacturers.

Immediate Release

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About Banpil Photonics, Inc.

Banpil Photonics is expanding tomorrow's technology through innovations in optics and electronics. The company has developed an extensive IP portfolio of high-speed interconnects, multispectral image sensors, and high-efficiency photovoltaic technologies available for licensing. Banpil innovations enable the development and manufacture of next generation low-cost, high-speed electrical interconnects for chip-to-chip, chip-to-board, board-to-board, and rack-to-rack applications; multispectral image sensors for automotive & medical imaging, mobile, security, remote-sensing, and communication applications; and photovoltaic technology for solar cell applications. For more information, visit www.banpil.com.

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